



Material Content Data Sheet



Sales Product Name	IPD640N06L G	Issued	17. February 2022
MA#	MA005698049		
Package	PG-TO252-3-311	Weight*	312.98 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.980	0.31	0.31	3130	3130
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137	
	non noble metal	iron	7439-89-6	0.143	0.05		458	
	non noble metal	copper	7440-50-8	143.098	45.71	45.77	457217	457812
wire	non noble metal	aluminium	7429-90-5	0.691	0.22	0.22	2207	2207
encapsulation	inorganic material	antimonytrioxide	1309-64-4	2.013	0.64		6433	
	plastics	brominated resin	-	2.157	0.69		6892	
	organic material	carbon black	1333-86-4	2.301	0.74		7352	
	plastics	epoxy resin	-	19.413	6.20		62028	
	inorganic material	silicondioxide	60676-86-0	117.919	37.68	45.95	376765	459470
leadfinish	non noble metal	tin	7440-31-5	3.740	1.20	1.20	11950	11950
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	276	277
solder	non noble metal	tin	7440-31-5	0.024	0.01		76	
	noble metal	silver	7440-22-4	0.030	0.01		95	
	non noble metal	lead	7439-92-1	1.136	0.36	0.38	3630	3801
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.13	6.14	61274	61353
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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